Worldsemi

Features and Benefits

- The control circuit and RGB chip are integrated in a 5050 components, to form an external control pixel.
- Intelligent Reverse-connection protection.The components will not be damaged when the 5V power supply is reversed.
- Using the built-in signal reshaping circuit to achieve the signal waveform shaping, and no distortion of waveform of signal takes place.
- The gray levels of each pixel are of 256 levels, which achieves "256*256*256=16777216" full-color display, and the refresh frequency reaches to 2KHz.
- Serial cascade interface, data receiving and decoding depend on just one signal line.
- Dual-signal wires version, signal break-point continuous transmission.
- Any two point the distance more than 2M transmission signal without any increase circuit.
- When the refresh rate is 30fps, cascade numbers is at least 1024 pixels.
- Data transmitting at speeds of up to 800Kbps.
- Good color consistency reliability, high cost-effective.
- NO extra components needed, even the capacitor.

Applications

- Consumer Electronics.
- Landscape lighting fields.
- Computer peripheral products, games devices and machinery equipment etc.

General description

WS2813B-V5/W is an intelligent control LED light source that the control circuit and RGB chip are integrated in a package of 5050 components. Its internal include intelligent digital port data latch and signal reshaping amplification drive circuit. Also include a precision internal oscillator and a voltage programmable constant current control part, which achieves highly consistent color effect.

Dual-signal wires version, signal break-point continuous transmission. Any pixel's failure won't affect signal transfer and total emitting effect.

The data transfer protocol use single NZR communication mode. After the pixel power-on reset, the DIN port receive data from controller, the first pixel collect initial 24bit data then sent to the internal data latch, the other data which reshaping by the internal signal reshaping amplification circuit sent to the next cascade pixel through the DO port. After transmission for each pixel, the signal to reduce 24bit. Every pixel adopts auto-reshaping transmit technology, making the pixel cascade numbers are not limited to the signal transmission, only relate to the speed of signal transmission.
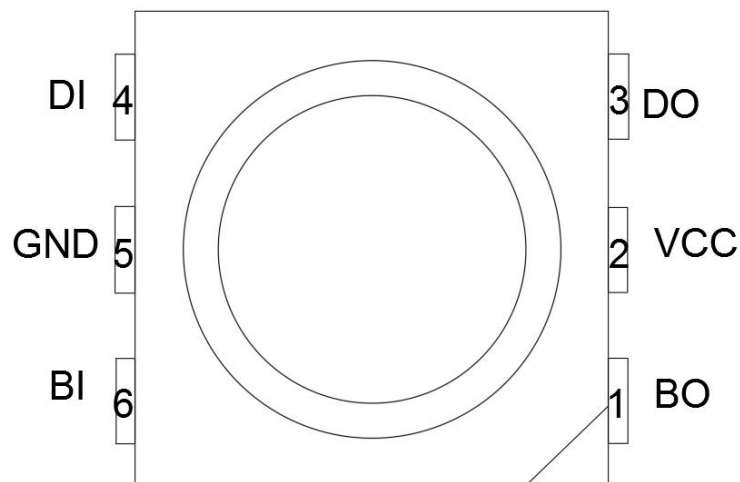
Refresh Frequency updates to **2KHz**, Low Frame Frequency and no Flicker appear in HD Video Camera.

RESET time>**280μs**, it won't cause wrong reset while interruption, it supports the lower frequency and inexpensive MCU.

http://www.world-semi.com

Mechanical Dimensions（Unit:mm）
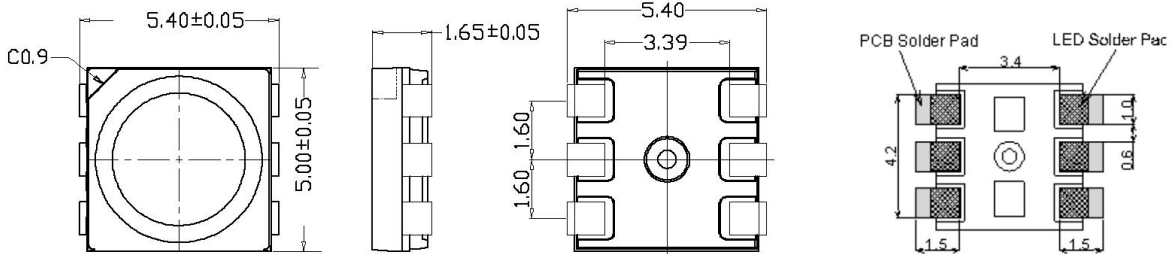
PIN Configuration

PIN Configuration

NO.	Symbol	PIN	Function description
1	BO	BO	Backup Control data signal output
2	VCC	VCC	LED POWER SUPPLY
3	DO	DO	Control data signal output
4	DIN	DIN	Control data signal input
5	GND	GND	Data & Power Grounding
6	BIN	BIN	Backup Control data signal input

Absolute Maximum Ratings (T$_A$=25℃, Vcc=5V, V$_{SS}$=0V)

Parameter	Symbol	Ratings	Unit
Power supply voltage	VCC	+3.7~+5.3	V
Logical Input Voltage	V$_I$	**-0.3V～VDD+0.7V**	V

Electrical Characteristics (T_A=25℃, Vcc=5V, V_{SS}=0V**)**

Parameter	Symbol	Min.	Tpy.	Max.	Unit	Conditions
Input Current	I_I	——	——	±1	μA	V_I=V_{DD}/V_{SS}
High-level Input	V_{IH}	0.7VDD	——	VDD+0.7V	V	D_{IN}
Low-level Input	V_{IL}	-0.3V	——	0.7V	V	D_{IN}

Switching Characteristics (T_A=25℃, Vcc=5V, V_{SS}=0V**)**

Parameter	Symbol	Min	Tpy	Max	Unit	Condition
Transmission Delay Time	t_{PLZ}	——	——	300	ns	CL=15pF, DIN→DOUT, RL=10KΩ
Fall time	t_{THZ}	——	——	120	μs	CL=300pF, OUTR/OUTG/OUTB
Input-capacitance	C_I	——	——	15	pF	——

LED Characteristics

Parameter	Symbol	Color	Quiescent Current: <0.6mA			Test DC=5V	
			Min	Tpy	Max	Unit	Working current
Brightness	IV	Red	300	380	600	mcd	16mA
		Green	800	1050	1500		
		Blue	200	270	400		
Wavelength	λd	Red	620	623	630	nm	16mA
		Green	510	520	520		
		Blue	465	471	475		

Data Transfer Time：

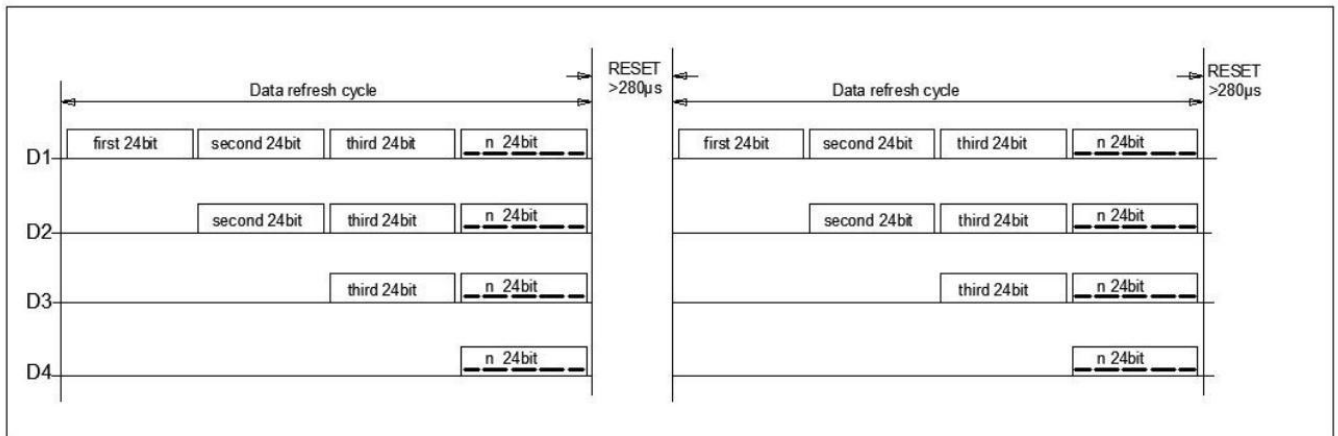|		
T0H	0-code, High-level time	220ns~380ns
T1H	1-code, High-level time	580ns~1μs
T0L	0-code, Low-level time	580ns~1μs
T1L	1-code, Low-level time	580ns~1μs
RES	Frame unit, Low-level time	> 280μs
T0H+T0L、T1H+T1L≥1.25μs		

Timing waveform

Sequence chart
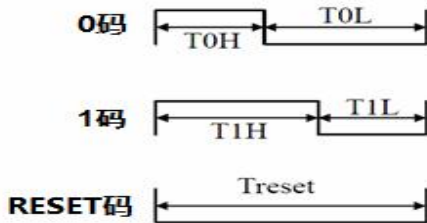
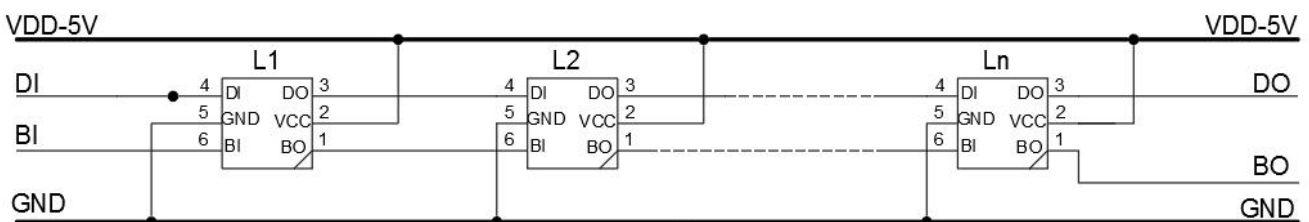### Cascade method
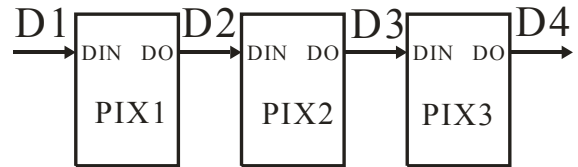
Data Transmission Method

Note: D1 is the data from MCU, and D2, D3, D4 are from Cascade Circuits.
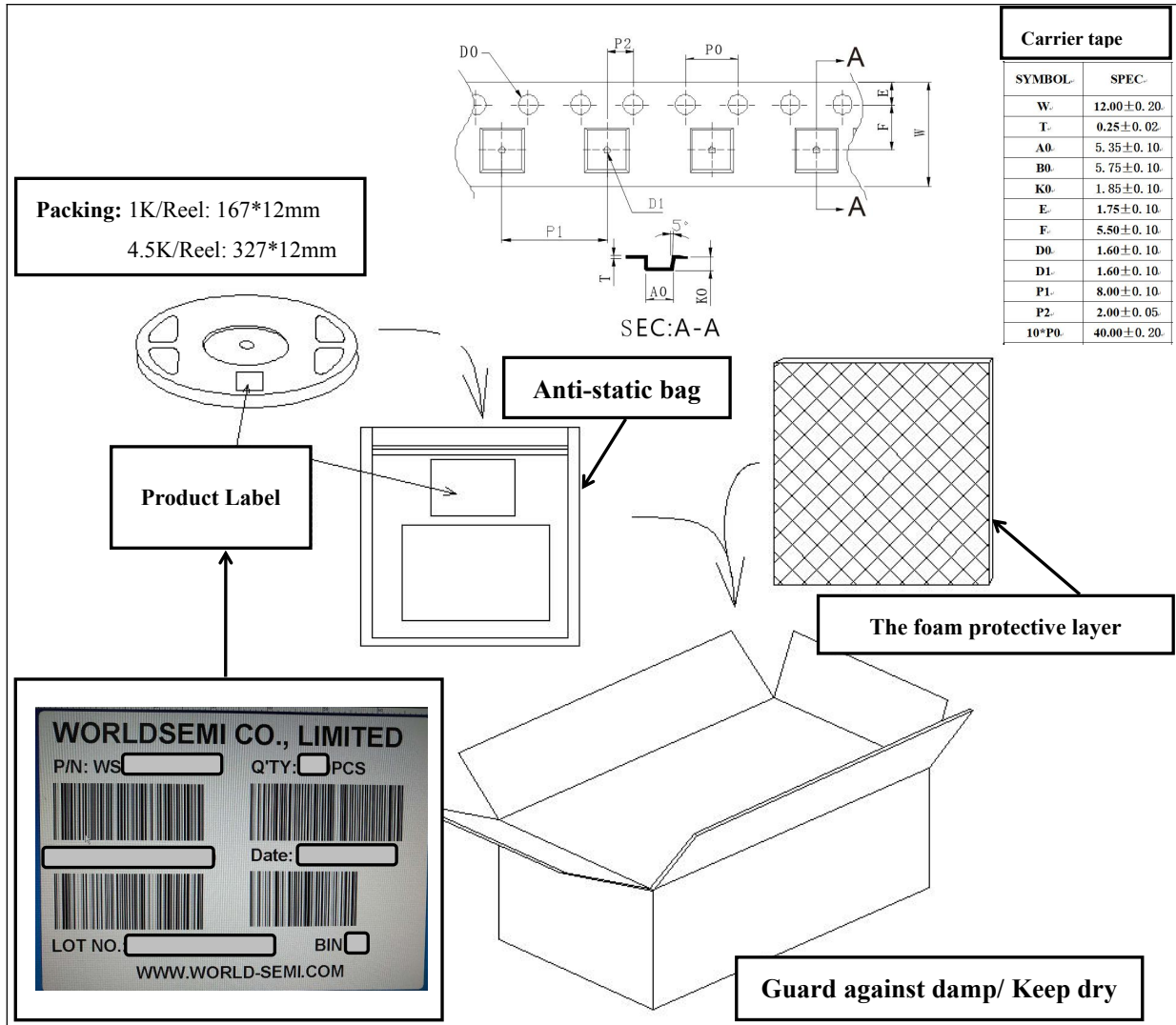
Composition of 24bit data

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4	R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0

Note: Data transmit in order of GRB, high bit data is first.

Typical application circuit

http://www.world-semi.com

Packing Standard

Carrier tape

SYMBOL	SPEC
W	12.00±0.20
T	0.25±0.02
A0	5.35±0.10
B0	5.75±0.10
K0	1.85±0.10
E	1.75±0.10
F	5.50±0.10
D0	1.60±0.10
D1	1.60±0.10
P1	8.00±0.10
P2	2.00±0.05
10*P0	40.00±0.20

Packing: 1K/Reel: 167*12mm

4.5K/Reel: 327*12mm

Product Label

Anti-static bag

SEC:A-A

The foam protective layer

WORLDSEMI CO., LIMITED
P/N: WS　　　　 Q'TY:　PCS

Date:

LOT NO.　　　　　 BIN
WWW.WORLD-SEMI.COM

Guard against damp/ Keep dry

Top SMD LED Using Instructions

1.Summary

To make the best use of WORLDSEMI's LED, please refer to the below precautions, they are of same usage method as other electronic components.

2. Cautions

2.1 Dust & Cleaning

http://www.world-semi.com

The surface of the LED is encapsulated with modified epoxy resin because it plays a very good role in protecting the optical performance and aging resistance. The modified epoxy resin is easy to stick with dust and must be kept clean. When there's a certain amount of dust on the surface of the LED, it won't affect brightness, but dust proof should be taken care of. Promoting the use of unsealed package in preference to others and the assembled LEDs should be placed in a clean container. Avoid using the organic solvents to clean the dust on the LED surface and it's necessary to confirm whether the cleaning fluid will dissolve the LED.Do not clean the LEDs by the ultrasonic. Some parameters affecting the LED performance must be evaluated if have no alternative but to the ultrasonic cleaning method, such as ultrasonic power, baking time and assembly conditions, etc.

2.2 Moisture-proof packaging

TOP SMD LEDs are moisture sensitive components. LEDs are packaged in aluminum foil bag to prevent from absorbing moisture during transport and storage. A desiccant is placed in the bags to absorb moisture. If the LED absorbs moisture, then it evaporates and expands when in reflow process, which may break the colloid from the bracket and damage the optical performance of LED. Moisture proof packaging is to avoid moisture in the packaging bag, but usually the protection time can only last for 1 ~ 2 months. The Moisture Sensitivity Level of WORLDSEMI's LED is: **LEVEL 5a**. Please refer to the definition of material Moisture Sensitivity Level(MSL) specified in IPC/JEDECJ-STD-020 when SMT.

Tabel I - IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification

MSL Level	Workshop Life	
	Time	Conditions
LEVEL1	Unlimited	≤30℃/85%RH
LEVEL2	1 Year	≤30℃/60%RH
LEVEL2a	4 Weeks	≤30℃/60%RH
LEVEL3	168 Hours	≤30℃/60%RH
LEVEL4	72 Hours	≤30℃160%RH
LEVEL5	48 Hours	≤30℃/60%RH
LEVEL5a	**24 Hours**	**≤30℃/60%RH**
LEVEL6	Take-out and Use immediately	≤30℃/60%RH

2.3. SMT Requirement：

2.3.1 It is recommended to unpack the LED before SMT and put the whole roll into the oven for dehumidification and drying (baking at 70 ~ 75 ℃ for ≥ 24h);

2.3.2 The product is taken out of the oven to the completion of high-temperature soldering (including multiple high-temperature operations/operations such as reflow soldering, tin immersion, wave soldering, and heating maintenance), and the time period is controlled within 24 hours (under the conditions of T<30℃, RH<60%) ;

2.3.3SMT shall be completed as soon as possible for LED pastes on PCBA after printing solder paste, and it is recommended not to exceed 1H;

2.3.4 Bulk LEDs such as production surplus, machine throwing materials, and maintenance materials cannot be used directly if they are exposed to the air for a long time. It is recommended to dehumidify and dry before use. Whole roll baking: 70～75℃＊≧24H or bulk material baking: 120℃＊4H.
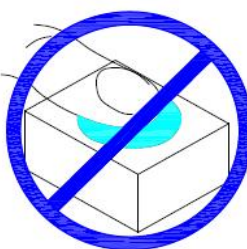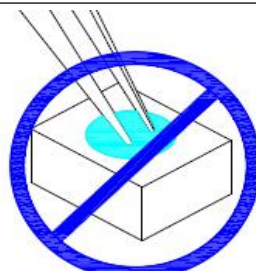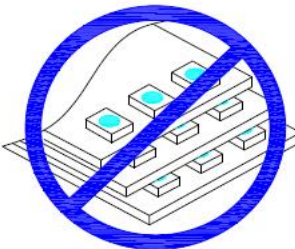
3.SMT Reflow

Refer to the parameters listed below, the experimental results prove that the TOP SMD LED meets the JEDEC J-STD-020C standards. As a general guideline, it is recommended to follow the SMT reflow temperature curve recommended by the solder paste manufacturer.

Temperature curve description	Range
30 ℃ ~ 150 ℃ preheating slope	1～4 ℃/s
30 ℃ ~ 150 ℃ preheating time	60～120 s
Constant temperature slope of 150 ℃ ~ 200 ℃	0～3 ℃/s
Constant temperature time of 150 ℃ ~ 200 ℃	60～120 s
LIQUID REGION temperature	217℃
Peak Temperature (Tp)	245℃
Reflow slope	0～3 ℃/s
Reflow time	45-90 s
cooling rate	-4～0 ℃/s
Room Temperature to Peak Holding Time	<6 min
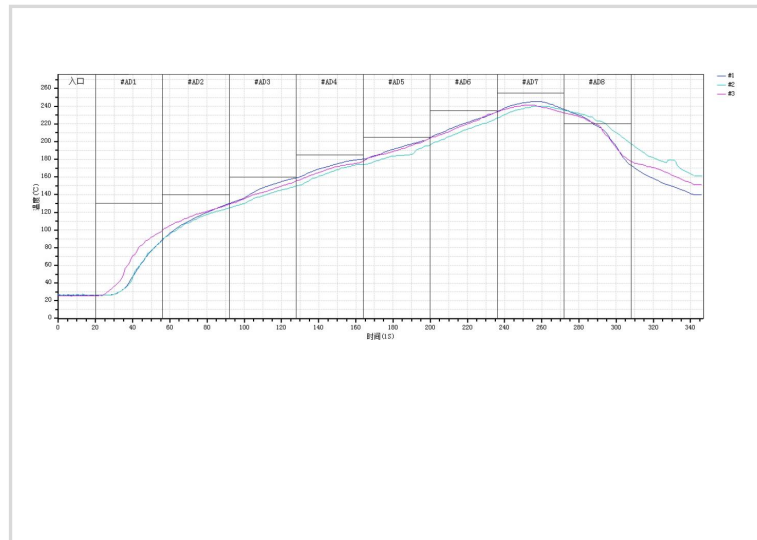
Remarks: 1. All temperatures referred are measured on the surface of the package body.

4. Assembly Precautions

1. Clip the LED from its side.	2. Neither directly touch the gel surface with the hand or sharp instrument, it may damage its internal circuit.	3. Not to be double stacked, it may damage its internal circuit.	4. Can not be stored in or applied in the acidic sites of PH<7.

http://www.world-semi.com

Modify Record

Version №	Status Bar	Modify Content Summary	Date	Reviser	Approved
V1.0	N	New	20170523	Shen JinGuo	Yin HuaPing
V1.1	M	Absolute Maximum Ratings	20171009	Shen JinGuo	Yin HuaPing
V1.2	M	Maximum ratings, Data Transfer Time	20180207	Shen JinGuo	Yin HuaPing
V2.0	M	"The transparent sealing silica gel" changed to "The opaque Modified Epoxy Resin". Refers to PRECAUTIONS	20180425	Shen JinGuo	Yin HuaPing
V3.0	M	Logical Input Voltage；Brightness adjustment；Precautions	20180719	Shen JinGuo	Yin HuaPing
V4.0	M	Driver IC upgraded; No extra components needed.	20190423	Shen JinGuo	Yin HuaPing
V5.0	M	On the basis of V4.0, enhance the internal filtering effect of the driver IC and remove the internal packaging capacitance.	20191020	Shen JinGuo	Yin HuaPing
V6.0	M	The colloid is changed to mist, part number is changed to WS2813B-V5/W	20211202	Yu XingHui	Yin HuaPing

Remarks:

1．Initial version: V1.0；Parameter added or modified, version number plus "0.1", for example: V1.0→ V1.1

2．Major version design or more parameters modified, version number plus "1.0", for example: V1.0→V2.0

3．With no version number attached to part number

4．Status bar: N--New, A--Add, M--Modify, D--Delete

http://www.world-semi.com